

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Yuan-Hsiang Lung</td> <td>04/19/2012</td> </tr> <tr> <td>Kuei-Shun Chen</td> <td>04/19/2012</td> </tr> <tr> <td>Meng-Wei Chen</td> <td>04/19/2012</td> </tr> <tr> <td>Chia-Ying Lee</td> <td>04/19/2012</td> </tr> </tbody> </table>		Name	Execution Date	Yuan-Hsiang Lung	04/19/2012	Kuei-Shun Chen	04/19/2012	Meng-Wei Chen	04/19/2012	Chia-Ying Lee	04/19/2012
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Kuei-Shun Chen	04/19/2012										
Meng-Wei Chen	04/19/2012										
Chia-Ying Lee	04/19/2012										
RECEIVING PARTY DATA											
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.										
Street Address:	No. 8, Li-Hsin Road 6										
City:	Hsin-Chu										
State/Country:	TAIWAN										
Postal Code:	300-77										
PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13451605</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13451605						
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Application Number:	13451605										
CORRESPONDENCE DATA											
Fax Number:	(214)200-0853										
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>											
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ATTORNEY DOCKET NUMBER:	24061.2085										
NAME OF SUBMITTER:	Rachel L.I. Davis										
Total Attachments: 3 source=2085_Assignment#page1.tif source=2085_Assignment#page2.tif source=2085_Assignment#page3.tif											

OP \$40.00 13451605

Docket No.: 2011-1472 / 24061.2085
Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|------------------|----|--|
| (1) | Yuan-Hsiang Lung | of | Pu-Ting 3rd Road 88, East District
Hsinchu City, Taiwan, R.O.C. |
| (2) | Kuei-Shun Chen | of | 27 393 Lane, Min-Hu Road
Hsin-Chu 300, Taiwan, R.O.C. |
| (3) | Meng-Wei Chen | of | 9F-1, No 198-2, Sec. 3, Huilai Road, Xitun District
Taichung City 407, Taiwan, R.O.C. |
| (4) | Chia-Ying Lee | of | No. 533, Xinzhuang Road, Xinzhuang District
New Taipei City 242, Taiwan, R.O.C. |

have invented certain improvements in

METAL CUT PROCESS FLOW

for which we have filed and executed an application for Letters Patent of the United States of America on April 20, 2012, as U.S. Serial No. 13/451,605; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue

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applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Yuan-Hsiang Lung

Residence Address: Pu-Ting 3rd Road 88, East District
Hsinchu City, Taiwan, R.O.C.

Dated: 2012.4.19

Yuan-Hsiang Lung
Inventor Signature

Inventor Name: Kuei-Shun Chen

Residence Address: 27 393 Lane, Min-Hu Road
Hsin-Chu 300, Taiwan, R.O.C.

Dated: 2012.4.19

Kuei-Shun Chen
Inventor Signature

Inventor Name: Meng-Wei Chen

Residence Address: 9F-1, No 198-2, Sec. 3, Huilai Road, Xitun District
Taichung City 407, Taiwan, R.O.C.

Dated: 2012.4.19

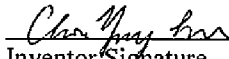
Meng Wei Chen
Inventor Signature

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Inventor Name: Chia-Ying Lee

Residence Address: No. 533, Xinzhuang Road, Xinzhuang District
New Taipei City 242, Taiwan, R.O.C.

Dated: 2012.4.19


Inventor Signature